

## High voltage fast-switching NPN power transistor

### Features

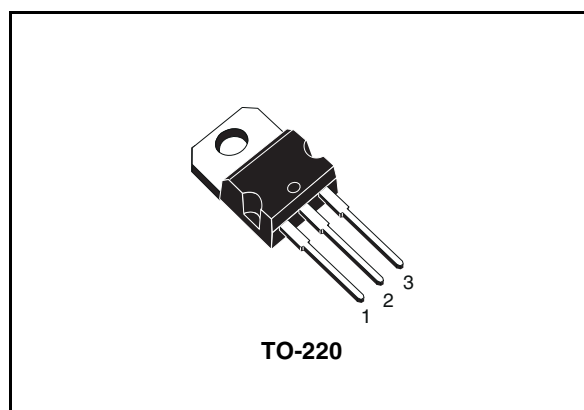
- High voltage capability
- Low spread of dynamic parameters
- Minimum lot-to-lot spread for reliable operation
- Very high switching speed

### Description

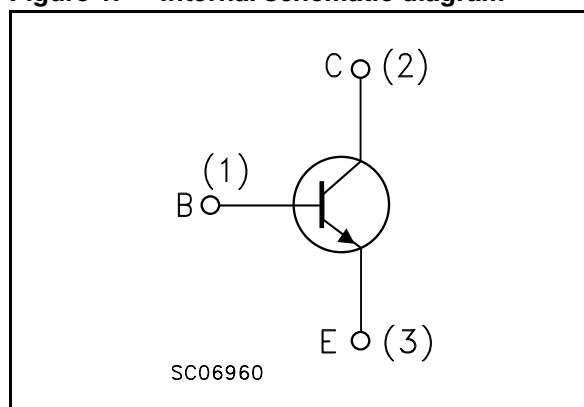
The device is manufactured using high voltage multi-epitaxial planar technology for high switching speeds and high voltage capability. It uses a cellular emitter structure with planar edge termination to enhance switching speeds. The device is designed for use as PFC in high frequency ballast half bridge voltage fed topology.

### Applications

- Electronic ballast for fluorescent lighting
- Dedicated for PFC solution in half-bridge voltage fed topology.



**Figure 1. Internal schematic diagram**



**Table 1. Device summary**

Order code	Marking	Package	Packaging
BUL805	BUL805	TO-220	Tube

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# 1 Electrical ratings

**Table 2. Absolute maximum rating**

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-emitter voltage ( $V_{BE} = 0$ )	800	V
$V_{CEO}$	Collector-emitter voltage ( $I_B = 0$ )	450	V
$V_{EBO}$	Emitter-base voltage ( $I_C = 0$ )	9	V
$I_C$	Collector current	5	A
$I_{CM}$	Collector peak current ( $t_P < 5\text{ms}$ )	10	A
$I_B$	Base current	2	A
$I_{BM}$	Base peak current ( $t_P < 5\text{ms}$ )	4	A
$P_{tot}$	Total dissipation at $T_C = 25^\circ\text{C}$	80	W
$T_{stg}$	Storage temperature	-65 to 150	$^\circ\text{C}$
$T_J$	Max. operating junction temperature	150	$^\circ\text{C}$

**Table 3. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max	1.56	$^\circ\text{C/W}$
$R_{thj-amb}$	Thermal resistance junction-amb max	62.5	$^\circ\text{C/W}$

## 2 Electrical characteristics

( $T_{\text{case}} = 25\text{ °C}$  unless otherwise specified)

**Table 4. Electrical characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{\text{CES}}$	Collector cut-off current ( $V_{\text{BE}} = 0$ )	$V_{\text{CE}} = 800\text{ V}$ $V_{\text{CE}} = 800\text{ V } T_{\text{C}} = 125\text{ °C}$			100 500	$\mu\text{A}$ $\mu\text{A}$
$I_{\text{CEO}}$	Collector cut-off current ( $I_{\text{B}} = 0$ )	$V_{\text{CE}} = 450\text{ V}$			250	$\mu\text{A}$
$V_{\text{EBO}}$	Emitter-base voltage ( $I_{\text{C}} = 0$ )	$I_{\text{E}} = 10\text{ mA}$	9			V
$V_{\text{CEO(sus)}}^{(1)}$	Collector-emitter sustaining voltage ( $I_{\text{B}} = 0$ )	$I_{\text{C}} = 10\text{ mA}$	450			V
$V_{\text{CE(sat)}}^{(1)}$	Collector-emitter saturation voltage	$I_{\text{C}} = 1\text{ A } I_{\text{B}} = 0.2\text{ A}$			0.4	V
		$I_{\text{C}} = 2\text{ A } I_{\text{B}} = 0.4\text{ A}$			0.6	V
		$I_{\text{C}} = 3\text{ A } I_{\text{B}} = 0.6\text{ A}$			0.8	V
$V_{\text{BE(sat)}}^{(1)}$	Base-emitter saturation voltage	$I_{\text{C}} = 1\text{ A } I_{\text{B}} = 0.2\text{ A}$			1.1	V
		$I_{\text{C}} = 2\text{ A } I_{\text{B}} = 0.4\text{ A}$			1.3	V
		$I_{\text{C}} = 3\text{ A } I_{\text{B}} = 0.6\text{ A}$			1.5	V
$h_{\text{FE}}$	DC current gain	$I_{\text{C}} = 10\text{ mA } V_{\text{CE}} = 5\text{ V}$	10			
		$I_{\text{C}} = 2\text{ A } V_{\text{CE}} = 5\text{ V}$	10		20	

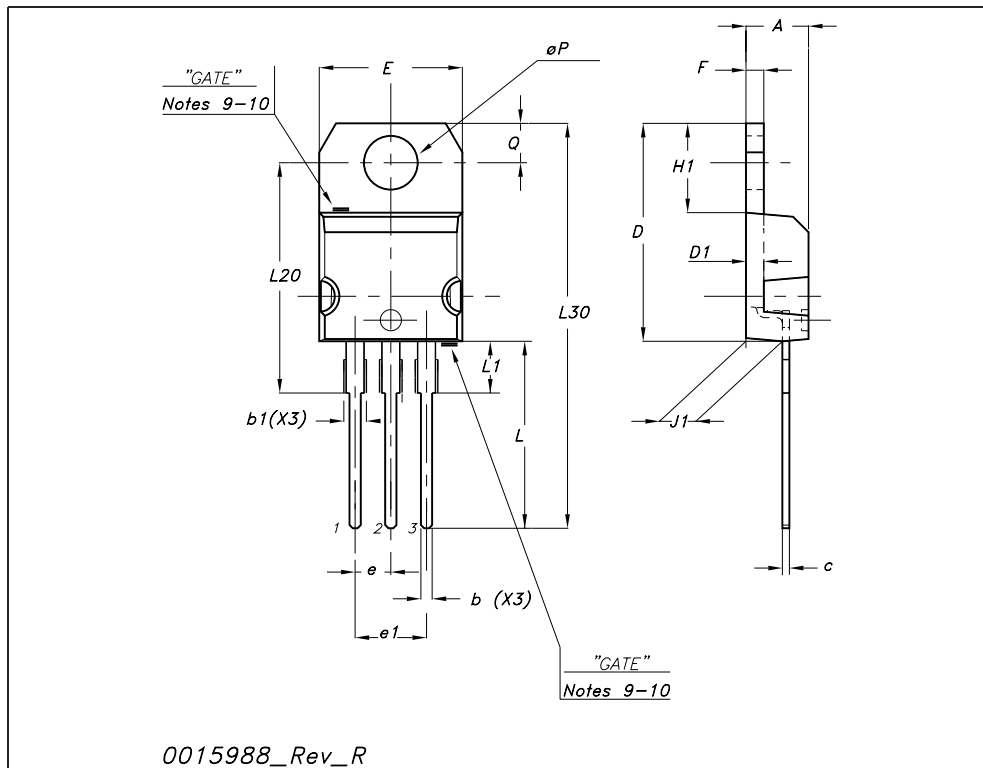
(1) Pulsed duration = 300  $\mu\text{s}$ , duty cycle  $\leq 1.5\%$

### 3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com)

TO-220 mechanical data

Dim	mm			inch		
	Min	Typ	Max	Min	Typ	Max
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.14		1.70	0.044		0.066
c	0.48		0.70	0.019		0.027
D	15.25		15.75	0.6		0.62
D1		1.27			0.050	
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.051
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
∅P	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



## 4 Revision history

**Table 5. Document revision history**

<b>Date</b>	<b>Revision</b>	<b>Changes</b>
19-May-2006	1	Initial release.
15-Jul-2008	2	Document status promoted from preliminary data to datasheet.

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